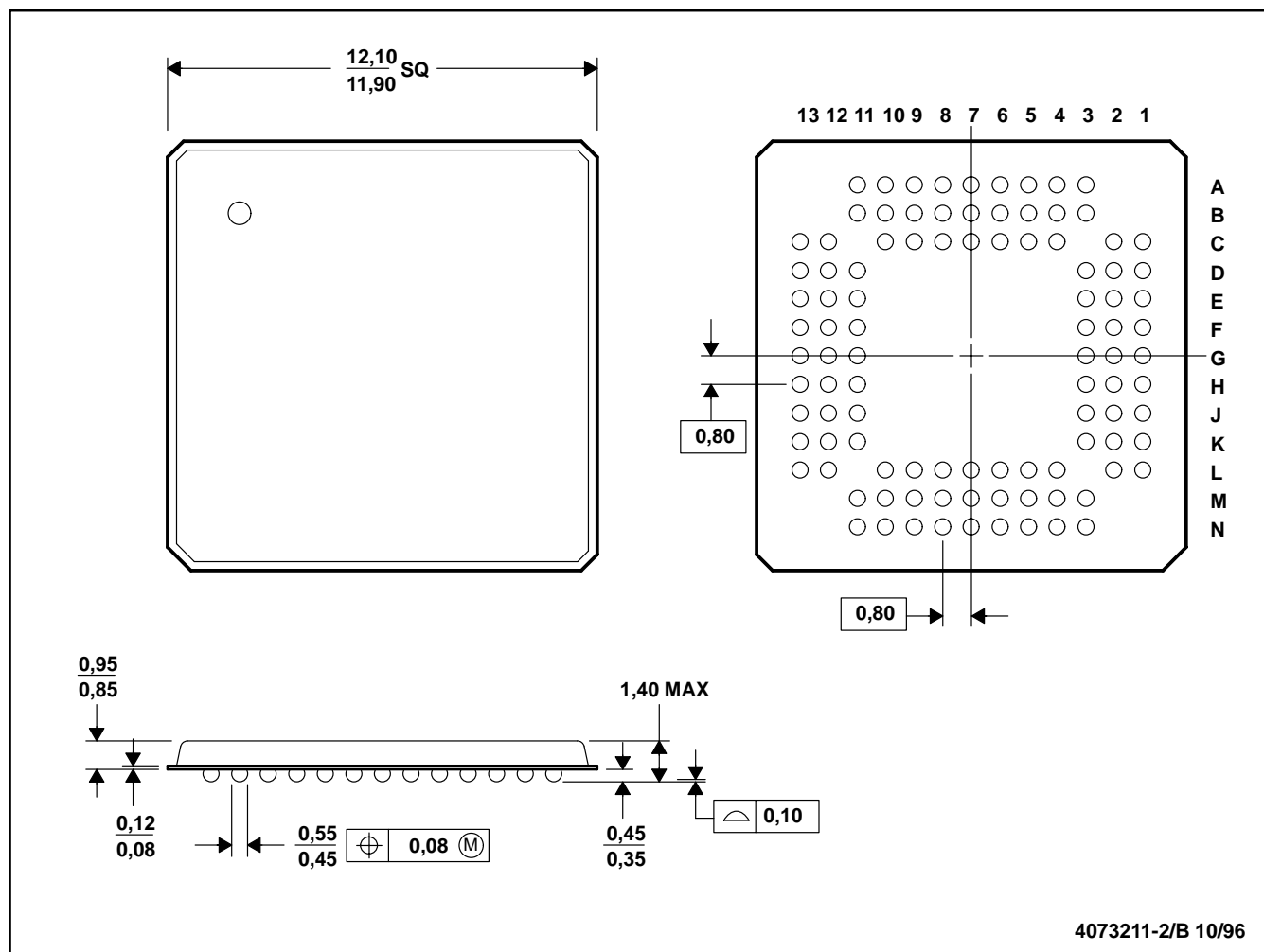


GGB (S-PBGA-N100)

PLASTIC BALL GRID ARRAY PACKAGE



NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. MicroStar™ BGA configuration

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